

Appl. No. 09/548,946  
Amdt. dated September 7, 2004  
Reply to Office Action of June 8, 2004

PATENT

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings of claims in the application:

Listing of Claims:

Claims 1-9. (canceled).

Claim 10. (currently amended) A chip device comprising:  
a leadframe including source and gate connections;  
a bumped die including solder bumps on a frontside, the bumped die being attached to the leadframe such that the solder bumps contact the source and gate connections;  
a copper clip attached to a backside of the bumped die and having an edge;  
a lead rail including leads and a v-groove, wherein the edge of the copper clip is in the v-groove; and  
solder paste coupling the edge of the copper clip and the v-groove of the lead rail;  
and  
apertures in the leadframe and being located under the die and being between the solder bumps.

Claim 11. (previously presented) A chip device in accordance with claim 10 wherein the copper clip is attached to the bumped die with solder paste.

Claim 12. (previously presented) A chip device of claim 10 wherein the lead rail comprises copper.

Claim 13. (canceled)

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Claim 14. (previously presented) A chip device of claim 10 wherein the lead frame and the lead rail comprise copper.

Claim 15. (new) A chip device of claim 10 wherein the bumped die comprises an underbump metallurgy layer.

Claim 16. (new) A chip device of claim 10 wherein the bumped die comprises an underbump metallurgy layer comprising Ti.

Claim 17. (new) A chip device of claim 10 wherein the edge of the copper clip terminates in the v-groove.

Claim 18. (new) A chip device of claim 10 further comprising flux on the leadframe.